

To: Technology Unit: 2829  
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From: W. Dani I Swayze, Jr.  
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MAY 27 2004  
**OFFICIAL**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**CERTIFICATION OF FACSIMILE TRANSMISSION**

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9306 on the date shown below:

*Tommie Chambers*  
Tommie Chambers

*5-27-04*  
Date

**FACSIMILE COVER SHEET**

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET	<input checked="" type="checkbox"/> AMENDMENT (16 Pages)
<input type="checkbox"/> NEW APPLICATION	<input checked="" type="checkbox"/> EOT (2 Month)
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<input type="checkbox"/> DIVISIONAL APP'N	
NAME OF INVENTOR(S): Potts	
RECEIPT DATE & SERIAL NO.: Serial No.: 10/055,445 Filing Date: 1/23/2002	
TITLE OF INVENTION: SEMICONDUCTOR WAFER WITH GROUPED INTEGRATED CIRCUIT DIE HAVING INTER-DIE CONNECTIONS FOR GROUP TESTING	
TI FILE NO.: TI-27832	DEPOSIT ACCT. NO.: 20-0668
FAXED: <i>5/27/04</i> DUE: 03/31/2004 ATTY/SEC'Y: WDS/tic	

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Texas Instruments Incorporated  
PO Box 655474, M/S 3999  
Dallas, TX 75265

MAY 27 2004

OFFICIAL

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Potts  
Serial No: 10/055,445  
Filed: 1/23/2002  
For: SEMICONDUCTOR WAFER WITH GROUPED INTEGRATED CIRCUIT  
DIE HAVING INTER-DIE CONNECTIONS FOR GROUP TESTING

Docket No: TI-27832  
Examiner: Geyer, Scott B.  
Art Unit: 2829

EXTENSION OF TIME

Assistant Commissioner For Patents  
Washington, DC 20231

<p align="center"><b>CERTIFICATION OF FACSIMILE TRANSMISSION</b></p> <p>I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at 703-872-9305 on <u>5-27-04</u>:</p> <p><i>Tommy Chambers</i> Tommy Chambers</p>
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Dear Sir:

Pursuant to 37 CFR 1.136(a), Applicant(s) respectfully petition(s) the Commissioner for an extension of the shortened statutory period for response in the above identified Application.

The fee for this extension is indicated below:

<input type="checkbox"/> One Month (\$110)	<input type="checkbox"/> Three Months (\$890)
<input checked="" type="checkbox"/> Two Months (\$390)	<input type="checkbox"/> Four Months (\$1,390)

Any further necessary extension of time is hereby requested. Charge any and all fees, or credit any overpayment, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,

*W. Daniel Swayze, Jr.*  
W. Daniel Swayze, Jr.  
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Reg. No. 34,478

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